

ABSTRACT OF THE DISCLOSURE

A bonding apparatus is constituted by a bonding tool, a substrate stage, a moving mechanism for moving the bonding tool and the substrate stage, an up-and-down mechanism for moving up and down said bonding tool, and a chip recognition camera. The bonding apparatus is configured so that a chip and a substrate are subjected to positioning on the basis of a recognition result of the chip recognition camera so that the chip is bonded onto the substrate. The chip recognition camera is disposed to be lower than a level of a substrate mounted surface of the substrate stage. A lower surface of the chip is recognized in a condition that the lower surface of the chip is located to be substantially on a level with a chip bonding surface of the substrate. Positioning of the chip and the substrate is performed by the recognition image.